



## Material Content Data Sheet



<b>Sales Product Name</b>		IPT111N20NFD		<b>Issued</b>		22. January 2018			
<b>MA#</b>		MA001383576							
<b>Package</b>		PG-HSOF-8-1		<b>Weight*</b>		788.34 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.025	0.89	0.89	8911	8911	
leadframe	non noble metal	iron	7439-89-6	0.421	0.05		534		
	inorganic material	phosphorus	7723-14-0	0.126	0.02		160		
	non noble metal	copper	7440-50-8	420.040	53.27	53.34	532814	533508	
wire	non noble metal	aluminium	7429-90-5	154.371	19.58	19.58	195817	195817	
encapsulation	organic material	carbon black	1333-86-4	2.900	0.37		3679		
	plastics	epoxy resin	-	31.901	4.05		40465		
	inorganic material	silicondioxide	60676-86-0	158.537	20.11	24.53	201101	245245	
leadfinish	non noble metal	tin	7440-31-5	6.479	0.82	0.82	8218	8218	
plating	non noble metal	nickel	7440-02-0	0.526	0.07		667		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.07	2	669	
solder	noble metal	silver	7440-22-4	0.150	0.02		191		
	non noble metal	tin	7440-31-5	0.120	0.02		153		
	non noble metal	lead	7439-92-1	5.745	0.73	0.77	7288	7632	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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